

PCN Number: 20131004000 **PCN Date:** 10/14/2013

Title: LM3445/LM3497 MSOP offload from TIEM to ASESH for assembly and test

Customer Contact: [PCN Manager](#) **Phone:** +1(214)480-6037 **Dept:** Quality Services

Proposed 1st Ship Date: 01/14/2014 **Estimated Sample Availability:** 10/31/2013

Change Type:		
<input checked="" type="checkbox"/>	Assembly Site	<input checked="" type="checkbox"/>
<input type="checkbox"/>	Design	<input type="checkbox"/>
<input type="checkbox"/>	Test Site	<input type="checkbox"/>
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>
<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>
<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>
<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>
<input type="checkbox"/>	Part number change	<input type="checkbox"/>

PCN Details

Description of Change:

Qualification of ASE Shanghai (ASESH) as an additional assembly/test site for selected devices in the MSOP package family. Material differences are noted below:

	TI Melaka	ASE Shanghai
Mold Compound	8096859	EN2000515
Mount Compound	8075531	EY1000063
Lead Finish	Matte Sn	NiPdAu

Upon expiry of this PCN TI will combine lead free solutions in a single standard part number, for example; LM3445MM/NOPB – can ship with both Matte Sn and NiPdAu.

Reason for Change:

Business Continuity

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Assembly Site		
TI Melaka	Assembly Site Origin (22L)	ASO: CU6
ASEH	Assembly Site Origin (22L)	ASO: ASH

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS
MADE IN: Malaysia
2DC: 20:
MSL '2 /260C/1 YEAR SEAL DT
MSL 1 /235C/UNLIM 03/29/04
OPT:
ITEM: 39
LBL: 5A (L)T0:1750

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

NiPdAu

G4 =
G3= MATTE Sn

Topside Device marking:
Assembly site code for TIEM= U
Assembly site code for ASEH = A

Product Affected:				
LM3445MM/NOPB	LM3445MMX/NOPB	LM3497MM/NOPB	LM3497MMX	
LM3445MM/S7002547	LM3445MMX/S7002546	LM3497MM/S7002611	LM3497MMX/NOPB	
LM3445MM/UKY8	LM3497MM	LM3497MM/UKY8	LM3497MMX/S7002539	
Qualification Data:				
This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.				
Qual Vehicle: LM3445MM/NOPB				
Package Construction Details				
Assembly Site:	ASESH	Mold Compound:	EN2000515	
# Pins-Designator, Family:	10, DGS	Mount Compound:	EY1000063	
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	Cu, 1.3mils	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size/Fail		
		Lot# 1	Lot# 2	Lot# 3
DOPL	Tj=125C (500hrs)	77/0	--	--
**Biased HAST	130C/85%RH 33.3psia (96 Hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
HTSL	150C (1000hrs)	77/0	--	--
ESDH	500V, 1000V, 1500V	3/0	--	--
ESDC	250V, 750V	3/0	--	--
Latch Up	25C, 125C, 150C	6/0	--	--
Notes ** - Preconditioning sequence: Level 1-260C.				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com